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| 1. Record Nr. | UNISA990000395250203316 |
| Titolo | Bande armate, banditi, banditismo e repressione di giustizia negli stati europei di antico regime : atti del convegno, Venezia 3-5 novembre 1985 / a cura di Gherardo Ortalli |
| Pubbl/distr/stampa | Roma : Jouvence, 1986 |
| Descrizione fisica | 566 p. ; 21 cm |
| Collana | Storia ; 20 |
| Disciplina | 364.1552094 |
| Soggetti | Brigantaggio - Europa - Sec. 16.-18. - Congressi - 1985 Congressi - Venezia - 1985 |
| Collocazione | 364.155 Ban 1 (ISE V 248) |
| Lingua di pubblicazione | Italiano |
| Formato | Materiale a stampa |
| Livello bibliografico | Monografia |

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| 2. Record Nr. | UNINA9910787022703321 |
| Titolo | 11th international congress molded interconnect devices : scientific proceedings : selected, peer reviewed papers from the 11th International Congress Molded Interconnect Devices (MID 2014), September 24-25, 2014, Nuremberg / Fuerth, Germany // edited by Jorg Franke [and three others] |
| Pubbl/distr/stampa | Pfaffikon, Switzerland : , : TTP, , 2014 Enfield, New Hampshire : , : Trans Tech Publications Ltd, , [date of distribution not identified] ©2014 |
| ISBN | 3-03826-636-1 |
| Descrizione fisica | 1 online resource (119 p.) |
| Collana | Advanced Materials Research, , 1662-8985 ; ; Volume 1038 |
| Disciplina | 621.367 |
| Soggetti | Molded interconnect devices Three-dimensional display systems |
| Lingua di pubblicazione | Inglese |
| Formato | Materiale a stampa |
| Livello bibliografico | Monografia |
| Note generali | Description based upon print version of record. |
| Nota di bibliografia | Includes bibliographical references at the end of each chapters and index. |
| Nota di contenuto | 11th International Congress Molded Interconnect Devices - Scientific Proceedings; Preface and Committees; Table of Contents; Chapter 1: Development and Prototyping; Method for the Identification and Comparison of Alternative Process Chains Focusing on Economics Efficiency Analysis during the Conceptual Design of Mechatronic Integrated Devices; Novel Approach for the Implementation of 3D-MID Compatible Routing Functionalities into Computer-Aided Design Tools; Optimized Process Sequences for Prototyping of Molded Interconnect Devices; Integration of Functional Circuits into FDM Parts Chapter 2: Printing TechnologiesPrinting of Functional Structures on Molded 3D Devices; Electrical Functionalization of Thermoplastics by Combining Plasmadust Coating and Aerosol Jet Printing; Production of Miniaturized Sensor Structures on Polymer Substrates Using Inkjet Printing; Progress in the Manufacturing of Molded Interconnected Devices by 3D Microcontact Printing; Chapter 3: Materials and Manufacturing; Characterization of Electromagnetic Properties of MID |

Materials for High Frequency Applications up to 67 GHz
Novel Laser Induced Metallization for Three Dimensional Molded
Interconnect Device Applications by Spray MethodExperimental
Investigation of Laser Sintering of Conductive Adhesive for Functional
Prototypes Produced by Embedding Stereolithography; MID Fabricated
by Ultrasonic Processing; Usage of Industrial Robots as Flexible
Handling Devices Supporting the Process of Three Dimensional
Conductive Pattern Generation; Chapter 4: Manufacturing Processes;
Study of MID Technologies for Automotive Lighting and Light Signaling
Devices; Chapter 5: Assembly Technologies and Inspection
Design and Solder Process Optimization in MID Technology for High
Power ApplicationsChapter 6: Quality and Reliability; Hot Pin Pull
Method - New Test Procedure for the Adhesion Measurement for 3D-
MID; Keywords Index; Authors Index

Sommario/riassunto

Collection of selected, peer reviewed papers from the 11 th
International Congress Molded Interconnect Devices (MID 2014),
September 24-25, 2014, Nuremberg / Fuerth, Germany. The 16 papers
are grouped as follows: Chapter 1: Development and Prototyping,
Chapter 2: Printing Technologies, Chapter 3: Materials and
Manufacturing, Chapter 4: Manufacturing Processes, Chapter 5:
Assembly Technologies and Inspection, Chapter 6: Quality and
Reliability.
